

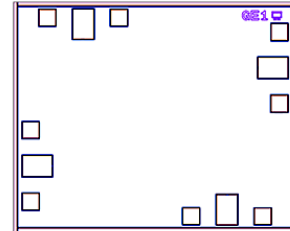
MMIC

Bi-Directional Coupler Die EBDC19-KA-D+

50Ω 5 to 43.5 GHz

The Big Deal

- Ultra-Wide Bandwidth, 5-43.5 GHz
- Excellent Coupling Flatness ± 0.6 dB typ over 20-40 GHz



Product Overview

Mini-Circuits' EBDC19-KA-D+ is a Bi-Directional Coupler die designed for wideband operation from 5 to 43.5 GHz with a nominal coupling of 18.7 dB over 20-40 GHz. Manufactured using GaAs IPD technology, it has excellent repeatability and excellent reliability.

Key Features

Feature	Advantages
Wideband, 5 to 43.5 GHz	A single Directional Coupler can be used in many applications, saving component count. Also ideal for applications such as 5G, military and instrumentation.
DC Passing up to 1.3A	DC current passing is helpful in applications where both RF & DC need to pass through the DUT, such as antenna mounted hardware.
Unpackaged die	Enables user to integrate it directly into hybrids.



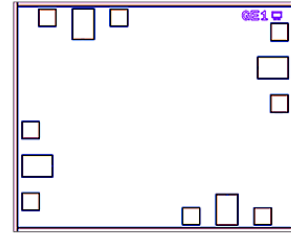
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50Ω 5 to 43.5 GHz

Product Features

- Wide bandwidth, 5 to 43.5 GHz
- Excellent Coupling Flatness, ±0.6 dB over 20 to 40 GHz
- Nominal Coupling 18.6 dB over 20 to 40 GHz
- DC passing



+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

Typical Applications

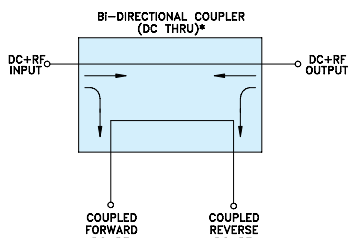
- 5G
- Instrumentation
- Military

Ordering Information: Refer to Last Page

General Description

Mini-Circuits' EBDC19-KA-D+ is a Bi-Directional Coupler die designed for wideband operation from 5 to 43.5 GHz with a nominal coupling of 18.7 dB over 20-40 GHz. Manufactured using GaAs IPD technology, it has excellent repeatability and excellent reliability.

Simplified Schematic and Pad description



Pad#	Function
1	Input
2	Output
4	Couple Forward
3	Couple Reverse
Die Bottom	Ground

Note: 1. Bond Pad material - Gold
2. Bottom of Die - Gold plated

Bonding Pad Position



Dimensions in μm, Typical

L1	L2	L3	L4	L5	H1	H2	H3	H4	H5	Die Thickness	Bond Pad #1, #3 Size	Bond Pad #2, #4 Size
134	392	1199	1456	1590	124	370	921	1166	1290	100	117 x 167	167 x 117



Electrical Specifications¹ at 25°C

Parameter	Frequency (GHz)	Min.	Typ.	Max.	Units
Frequency Range		5		43.5	GHz
Main Line Loss	5 - 10		0.3		dB
	10 - 20		0.6		
	20 - 40		0.6		
	40 - 43.5		0.6		
Nominal Coupling	5 - 10		25.6		dB
	10 - 20		21.0		
	20 - 40		18.7		
	40 - 43.5		19.5		
Coupling Flatness (\pm)	5 - 10		2.8		dB
	10 - 20		1.9		
	20 - 40		0.6		
	40 - 43.5		0.6		
Directivity	5 - 10		8.8		dB
	10 - 25		9.1		
	25 - 30		10		
	30 - 43.5		6.0		
Return Loss - Input / Output	5 - 10		15.6		dB
	10 - 20		13.7		
	20 - 40		14.7		
	40 - 43.5		16.0		
Return loss - CPL-FWD/CPL-REV	5 - 10		15.8		dB
	10 - 20		14.1		
	20 - 40		14.8		
	40 - 43.5		15.8		

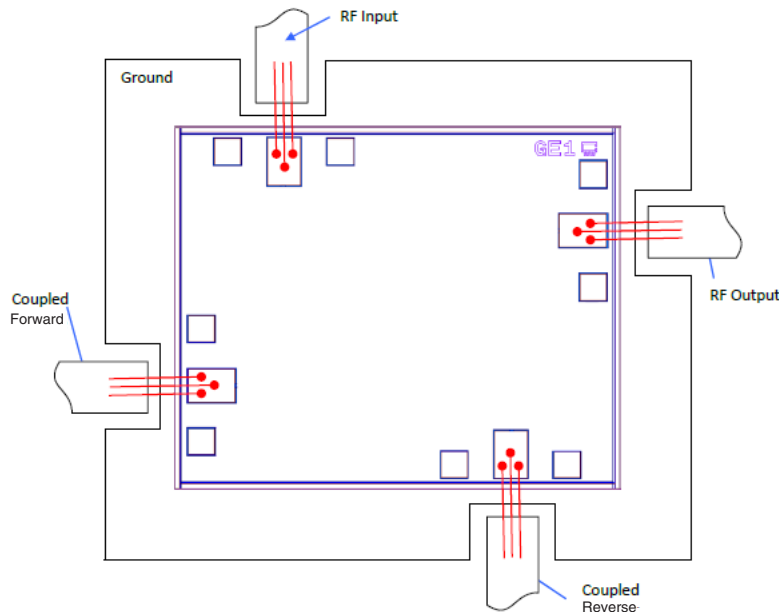
1. Measured on Die using MPI TITAN 200 μ m GSG probe

Absolute Maximum Ratings²

Parameter	Ratings
Operating Temperature	-40°C to 85°C
Power Input	1W Max.
Power into Coupled Port	1W Max.
DC Current	1.3A at 25°C. Derate linearly to 0.65A at 85°C

2. Permanent damage may occur if any of these limits are exceeded.
Electrical maximum ratings are not intended for continuous normal operation.

Assembly Diagram



Note: Ground bond wires are optional

Assembly and Handling Procedure

1. Storage
Dice should be stored in a dry nitrogen purged desiccators or equivalent.
2. ESD
MMIC coupler dice are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic protected material, which should be opened in clean room conditions at an appropriately grounded anti-static workstation. Devices need careful handling using correctly designed collets, vacuum pickup tips or sharp antistatic tweezers to deter ESD damage to dice.
3. Die Attach
The die mounting surface must be clean and flat. Using conductive silver filled epoxy, recommended epoxies are DieMat DM6030HK-PT/H579 or Ablestik 84-1LMISR4. Apply sufficient epoxy to meet required epoxy bond line thickness, epoxy fillet height and epoxy coverage around total die periphery. Parts shall be cured in a nitrogen filled atmosphere per manufacturer's cure condition. It is recommended to use antistatic die pick up tools only.
4. Wire Bonding
Bond pad openings in the surface passivation above the bond pads are provided to allow wire bonding to the dice gold bond pads. Thermosonic bonding is used with minimized ultrasonic content. Bond force, time, ultrasonic power and temperature are all critical parameters. Suggested wire is pure gold, 1 mil diameter. Bonds must be made from the bond pads on the die to the package or substrate. All bond wires should be kept as short as low as reasonable to minimize performance degradation due to undesirable series inductance.

